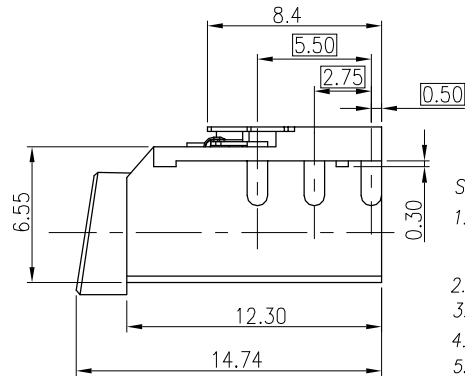
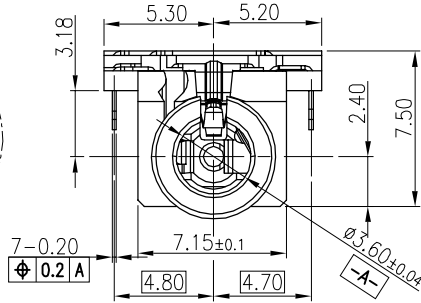
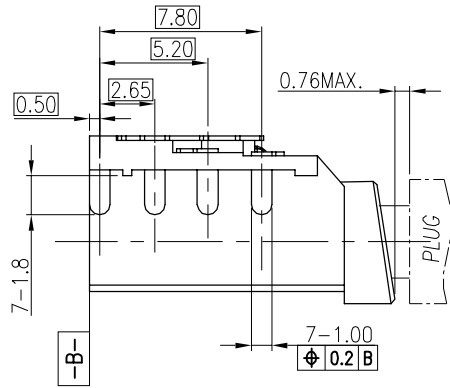
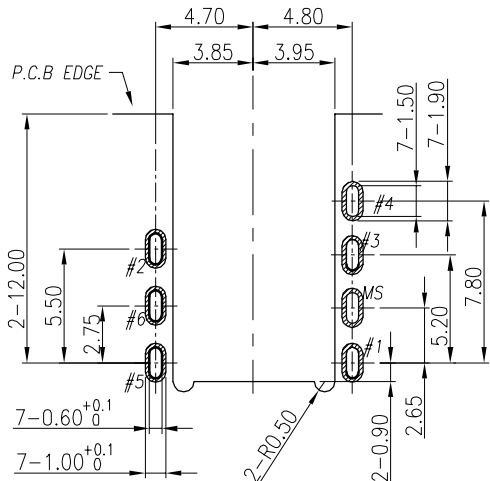


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.: T131229-6A	HM-JIANG	2014.08.03
B	ECN NO.: S140838	ANDY	2014.09.28



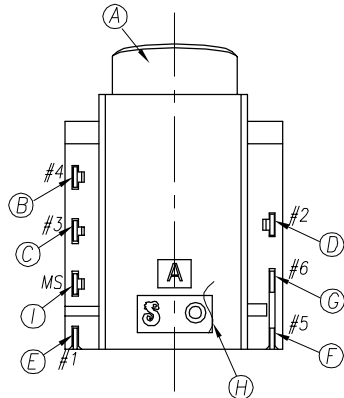
SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC .
- CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
- INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
- LIFE TEST: 5,000 CYCLES MIN.
- INSERTION FORCE: 0.3-3.0 Kgf ,
- WITHDRAWAL FORCE: 0.3-3.0 Kgf,
- AFTER TEST, CONTACT RESISTANCE: 100mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK " " ON TOP OF CONNECTOR.
- PACKING : TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:

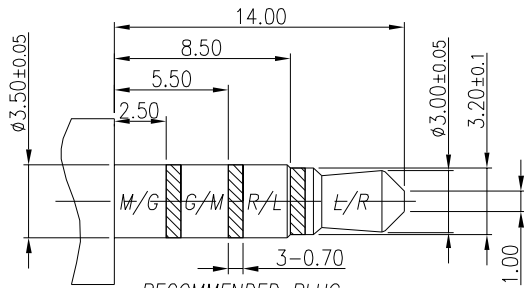
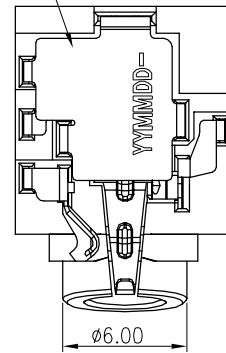


RECOMMENDED PCB LAYOUT

TOP VIEW ; TOL.±0.05

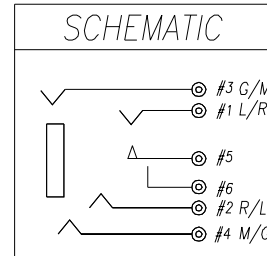
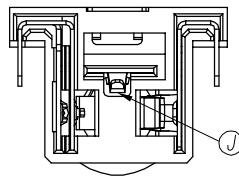


DATE CODE.



RECOMMENDED PLUG

Ø3.5 4-POLE STANDARD PLUG



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
J	DUMMY	1	STAINLESS STEEL, 0.2t	Ni 60u"Min.
I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60u"Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	TRANSFER TERMINAL	1	C5210-EH ,0.2T	GOLD FLASH ON CONTACT AREA; Matte Sn80u" ON SOLDER AREA; ALL OVER 50u" Ni.
E	TIP SPRING	1	COPPER ALLOY, 0.2t	
D	RING-A	1	COPPER ALLOY, 0.2t	Au 5u" ON CONTACT AREA; Matte Sn80u" ON SOLDER AREA; ALL OVER 50u" Ni.
C	EARTH	1	COPPER ALLOY, 0.2t	
B	RING-B	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE
X :±0.5	X :±2°	3.5Ø PHONE JACK
X.X :±0.3	X.X :±1°	DWN ANDY PART NO. 2SJ3095-031111F
X.XX :±0.2		CHKD CERRY SCALE 4:1 UNIT: mm
		APVD LIAO SIZE: A3 SHEET:1 OF 1 REV: B

CUSTOMER COPY